

HOSTAFORM® LM140LG - POM

Description

Hostaform® acetal copolymer grade LM140LG is a laser markable specialty grade of acetal copolymer formulated to provide good flow with a low gloss finish. Preliminary Data Sheet

Physical properties	Value	Unit	Test Standard
Density	1330	kg/m ³	ISO 1183
Melt volume rate, MVR	13	cm ³ /10min	ISO 1133
MVR temperature	190	°C	ISO 1133
MVR load	2,16	kg	ISO 1133
Mechanical properties	Value	Unit	Test Standard
Tensile modulus	1900	MPa	ISO 527-2/1A
Tensile stress at yield, 50mm/min	41	MPa	ISO 527-2/1A
Tensile strain at yield, 50mm/min	10	%	ISO 527-2/1A
Charpy notched impact strength, 23°C	3,1	kJ/m ²	ISO 179/1eA
Thermal properties	Value	Unit	Test Standard
Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
DTUL at 1.8 MPa	80	°C	ISO 75-1, -2

Typical injection moulding processing conditions

Pre Drying	Value	Unit	Test Standard
Drying time	3 - 4	h	-
Drying temperature	100 - 120	°C	-
Temperature	Value	Unit	Test Standard
Zone1 temperature	170 - 175	°C	-
Zone2 temperature	170 - 180	°C	-
Zone3 temperature	175 - 185	°C	-
Zone4 temperature	180 - 190	°C	-
Nozzle temperature	185 - 195	°C	-
Melt temperature	180 - 195	°C	-
Mold temperature	80 - 105	°C	-
Pressure	Value	Unit	Test Standard
Back pressure max.	40	bar	-
Speed	Value	Unit	Test Standard
Injection speed	slow	-	-

Other text information

Pre-drying

Predrying is required before processing to ensure a low gloss finish.

Injection molding

Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (I.E. general purpose 2:1 compression ratio) can result in unmelted particles and poor melt homogeneity. Using a high back pressure to make up for a low compression ratio may lead to excessive shear heating and deterioration of the material.

Melt Temperature: Preferred range 182-199 C (360-390 F). Melt temperature should never exceed 230 C (450 F).

Mold Surface Temperature: Preferred range 82-93 C (180-200 F) especially with wall thickness less than 1.5 mm (0.060 in.). May require mold temperature as high as 120 C (250 F) to reproduce mold surface or to assure minimal molded in stress. Wall thickness greater than 3mm (1/8 in.) may use a cooler (65 C/150 F) mold surface temperature and wall thickness over 6mm (1/4 in.) may use a cold mold surface down to 25 C (80 F). In general, mold surface temperatures lower than 82 C (180 F) may hinder weld line formation and produce a hazy surface or a surface with flow lines, pits and other included defects that can hinder part performance.

Characteristics

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Special Characteristics

Laser markable

Processing

Injection molding

Product Categories

Specialty

Delivery Form

Pellets

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General Disclaimer

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